

## **J-STD-020**

### **JOINT IPC/JEDEC STANDARD FOR MOISTURE/REFLOW SENSITIVITY CLASSIFICATION FOR NONHERMETIC SOLID STATE SURFACE-MOUNT DEVICES**

This document identifies the classification level of nonhermetic solid-state surface mount devices (SMDs) that are sensitive to moisture-induced stress.

It is used to determine what classification level should be used for initial reliability qualification.

Once identified, the SMDs can be properly packaged, stored and handled to avoid subsequent thermal and mechanical damage during the assembly solder reflow attachment and/or repair operation.

This revision now covers components to be processed at higher temperatures for lead-free assembly.